

MDT040000C	480 x 480	RGB + SPI Interface	TFT Module
Specification			
Version: 1		Date: 13/05/2022	
Revision			
1	11/05/2022	First issue	

Display Features			
Display Size	4.0"		
Resolution	480 x 480		
Orientation	Square		
Appearance	RGB		
Logic Voltage	3.3V		
Interface	RGB + SPI		
Brightness	340 cd/m ²		
Touchscreen	CTP		
Module Size	74.83 x 78.98 x 1.93 mm		
Operating Temperature	-20°C ~ +70°C	Created By	Checked By
Pinout	50 way FFC	RV	WE
Pitch	0.5 mm	Box Quantity	Weight / Display
		---	---

* - For full design functionality, please use this specification in conjunction with the ST7701S display driver specification.(Provided Separately)

Display Accessories	
Part Number	Description
MBID-50FP	50 Way FFC to cable and wires. Driven by any driver board that can be wired to a 1mm pitch SHDR-50V-S-B receptacle.
MDIB-CC1	Interconnect board for standard pitch pinouts to fine pitch wires. Providing pinouts for 2.54 pinout. 1.27, 1, 0.845, 0.8, 0.7, 0.65, 0.62,

Optional Variants	
Appearances	Voltage



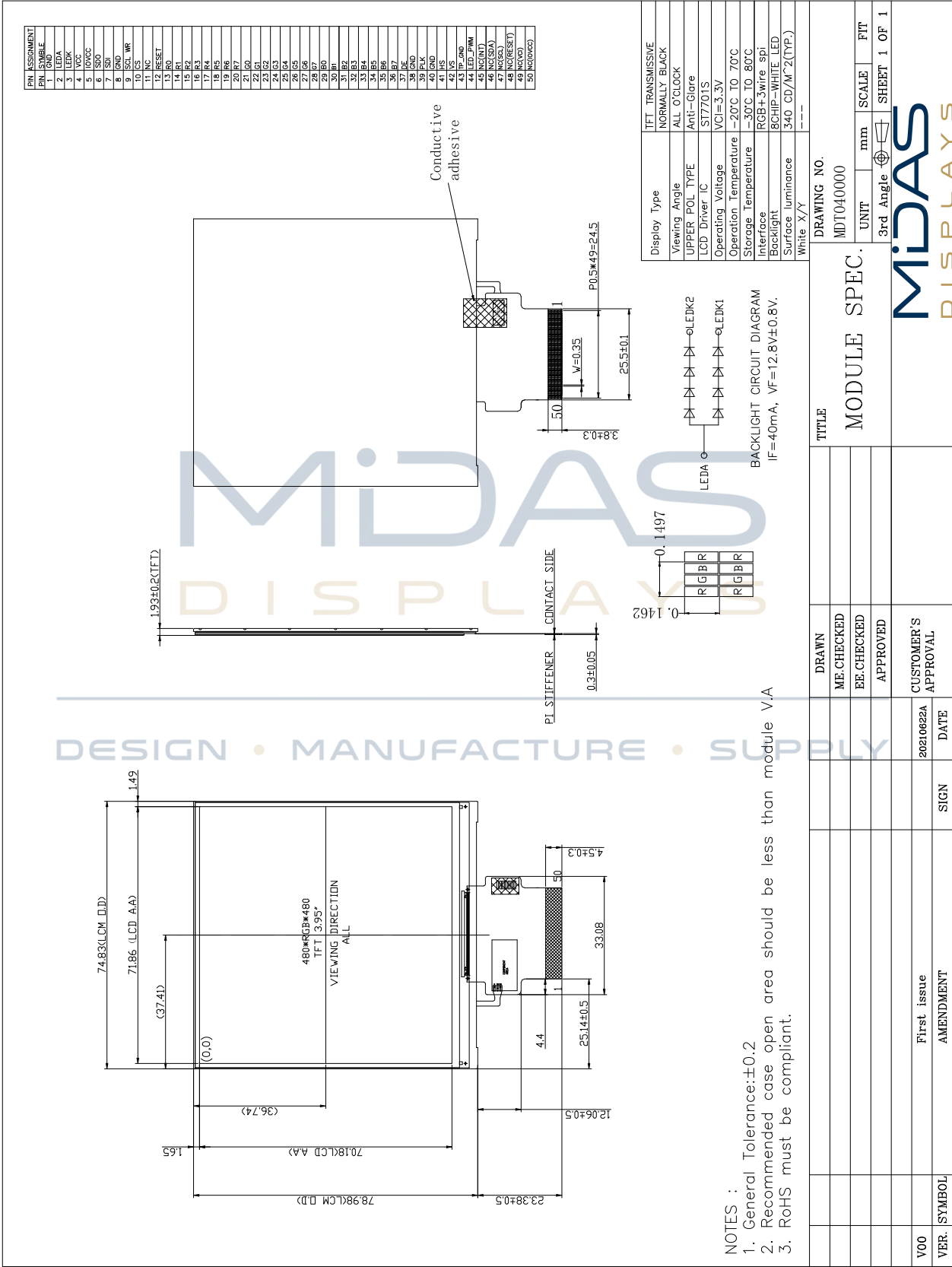
1. General Specification

Item	Contents	Unit
LCD TYPE	TFT/TRANSMISSIVE	
MODULE SIZE (W*H*T)	74.83*78.98*1.93	MM
ACTIVE SIZE (W*H)	71.86*70.18	MM
PIXEL PITCH (W*H)	0.1497*0.1462	MM
NUMBER OF DOTS	480*480	
LCD DRIVER IC	ST7701S	
INTERFACE TYPE	RGB+3WIRE SPI	
TOP POLARIZER TYPE	ANTI-GLARE	
RECOMMEND VIEWING DIRECTION	ALL	O'CLOCK
GRAY SCALE INVERSION DIRECTION	-	O'CLOCK
COLOR	16.7M	
BACKLIGHT TYPE	8-CHIP WHITE LED	
TOUCH PANEL TYPE	Capacitive	

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2. Mechanical Drawing

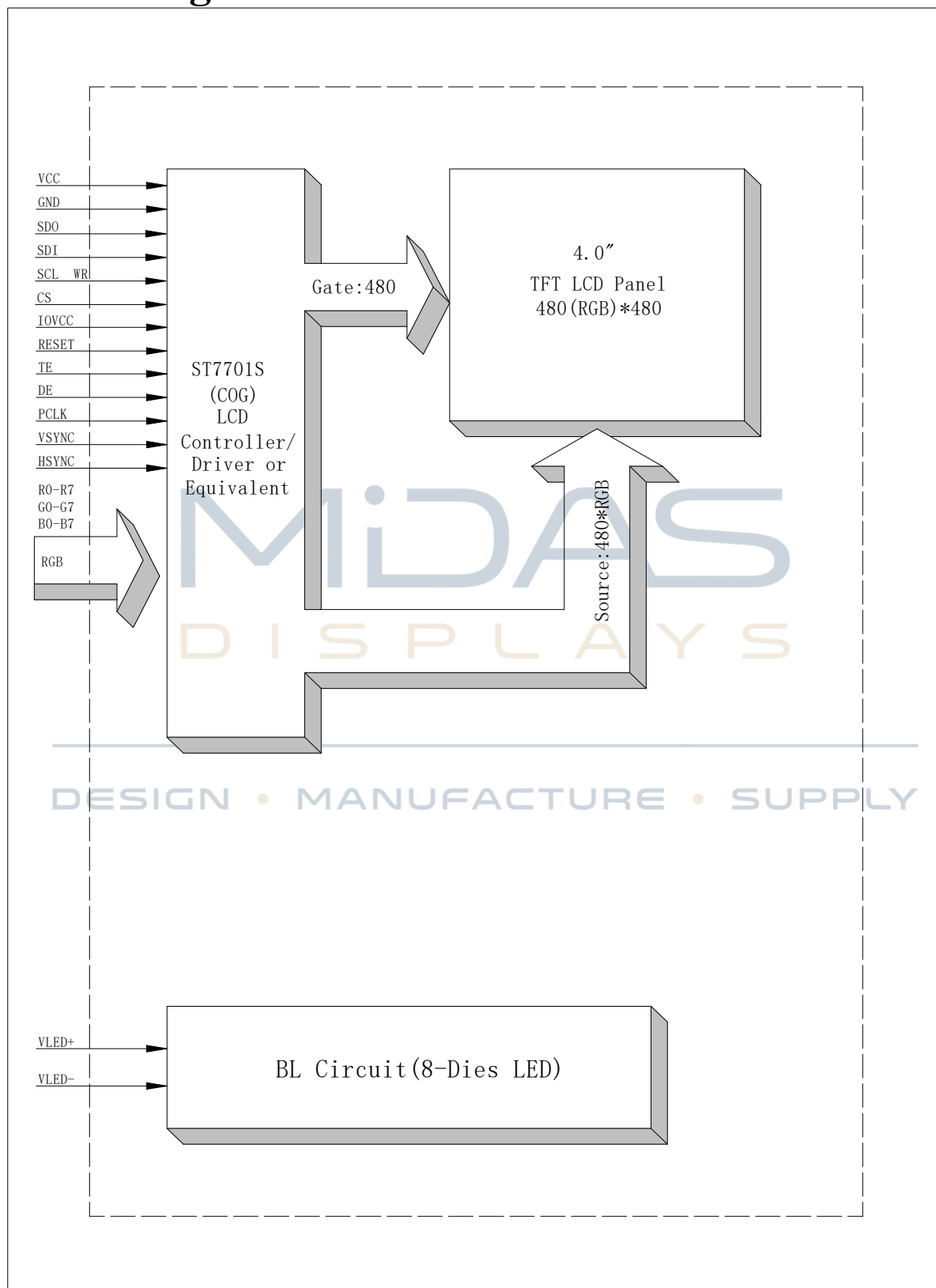


**Touch Panel Drawing available on
request, please contact
sales@midasdisplays.com**

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3. Block Diagram



4. Interface Pin Function

Pin No.	Symbol	Description
1	GND	Power ground.
2	LEDA	Anode of LED backlight.
3	LEDK	Cathode of LED backlight.
4	VCC	Power supply
5	IOVCC	I/O Digital Voltage
6	SDO	Serial clock input for SPI interface.
7	SDI	Serial data output pin used for the SPI Interface.
8	GND	Power ground.
9	SCL WR	Serial clock input for SPI interface.
10	CS	A chip select signal
11	NC	No connect
12	RESET	Reset pin.
13	R0	data bus
14	R1	data bus
15	R2	data bus
16	R3	data bus
17	R4	data bus
18	R5	data bus
19	R6	data bus
20	R7	data bus
21	G0	data bus
22	G1	data bus
23	G2	data bus
24	G3	data bus
25	G4	data bus
26	G5	data bus
27	G6	data bus
28	G7	data bus
29	B1	data bus
30	B2	data bus
32	B3	data bus
33	B4	data bus
34	B5	data bus
35	B6	data bus
36	B7	data bus
37	DE	Data enable signal for RGB interface operation
38	GND	Power ground.
39	PLK	Dot clock signal for RGB interface operation
40	GND	Power ground.
41	HS	Line synchronizing signal for RGB interface operation



42	VS	Frame synchronizing signal for RGB interface operation
43	TP-GND	TP Power ground
44	LED-PWM	BL Dimming Control Input.
45	NC	No connection.
46	NC	No connection.
47	NC	No connection.
48	NC	No connection.
49	NC	No connection.
50	NC	No connection.

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5. Absolute Maximum Ratings

Parameter	Symbol	Min	Max	Unit
Supply voltage for analog	VCC	-0.3	4.6	V
Supply voltage for logic	IOVCC	-0.3	4.6	V
Supply current (One LED)	I _{LED}		30	mA
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

Note: The absolute maximum rating values of this product are not allowed to be exceeded at any times. Should a module be used with any of the absolute maximum ratings exceeded, the characteristics of the module may not be recovered, or in an extreme case, the module may be permanently destroyed.

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6. Electrical Characteristics

6.1 Input Power

Item	Symbol	Min	Typ.	Max	Unit	Applicable terminal
Supply Voltage for Analog	VCC	2.7	3.3	3.6	V	
Supply Voltage for Logic	IOVCC	2.7	3.3	3.6	V	
Input Voltage	V _{IL}	GND	-	0.3IOVCC	V	
	V _{IH}	0.7 IOVCC	-	IOVCC		
Input leakage Current	I _{LKG}	-1		1	μA	

6.2 Backlight Driving Conditions

Item	Symbol	Value			Unit	Remark
		Min.	Typ.	Max.		
Voltage for LED Backlight	V _F	-	12.8	-	V	I _L =40mA
Current for LED Backlight	I _L		40		mA	
Power Consumption	P		0.576		W	
LED Life Time		30,000			Hr	Note

Note: Brightness to be decreased to 50% of the initial value at ambient temperature TA=25°C

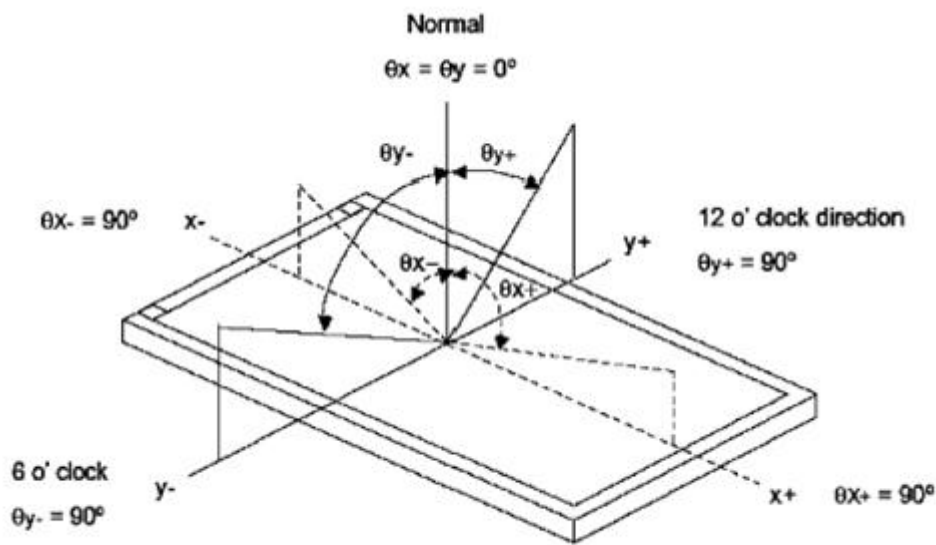


7. Optical Characteristics

ITEM		SYMBOL	CONDITIONS	SPECIFICATIONS			UNIT	NOTE
				MIN	TYP.	MAX		
Luminance		L	$I_L = 40\text{mA}$	270	340	480	Cd/m^2	
Contrast Ratio		CR	$\theta = 0^\circ$	700	900			
Response Time		T_{ON}	25°C	-	25		ms	
		T_{OFF}		-	-	-		
CIE Color Coordinate	Red	X_R	Viewing normal angle					
		Y_R						
	Green	X_G						
		Y_G						
	Blue	X_B						
		Y_B						
	White	X_W						
		Y_W						
Viewing Angle	Hor.	θ_{X+}	$\text{CR} \geq 10$	70	80		Degree	
		θ_{X-}		70	80			
	Ver.	θ_{Y+}		70	80			
		θ_{Y-}		70	80			
Uniformity	Un			80			%	



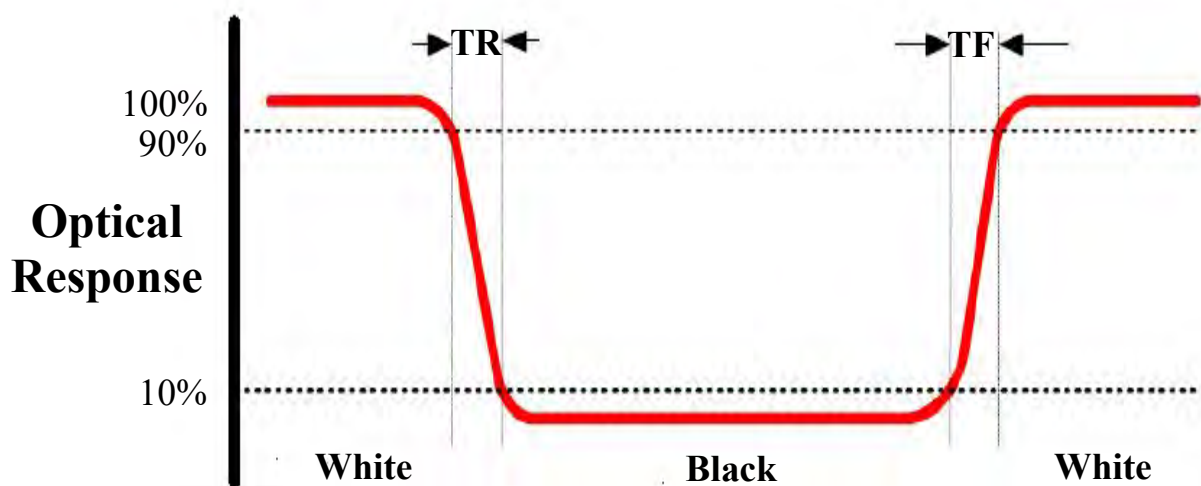
Note 1: Definition of Viewing Angle θ_x and θ_y :



Note 2: Definition of contrast ratio CR:

$$CR = \frac{\text{Luminance of white state}}{\text{Luminance of black state}}$$

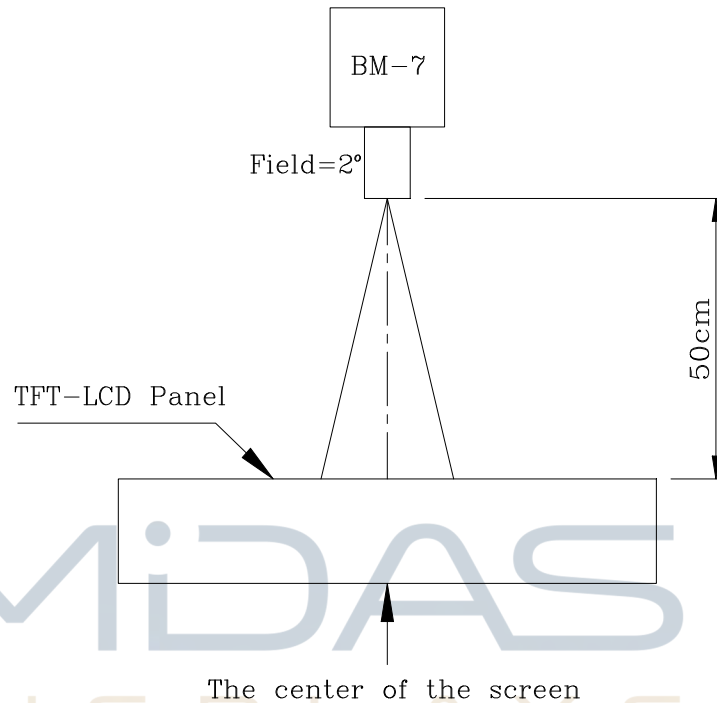
Note 3: Definition of Response Time (T_r, T_f)



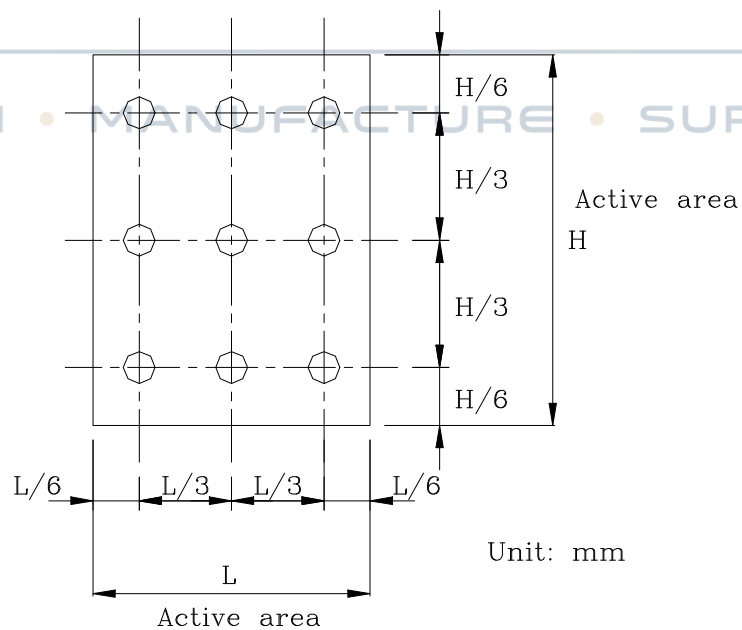
Note 4: Definition of Luminance

①The Brightness Test Equipment Setup

Field=2° (As measuring “black” image, field=2° is the best testing condition)



②The Brightness Test Point Setup



8. Timing Characteristics

8.1 Serial Interface Characteristics(3-line serial):

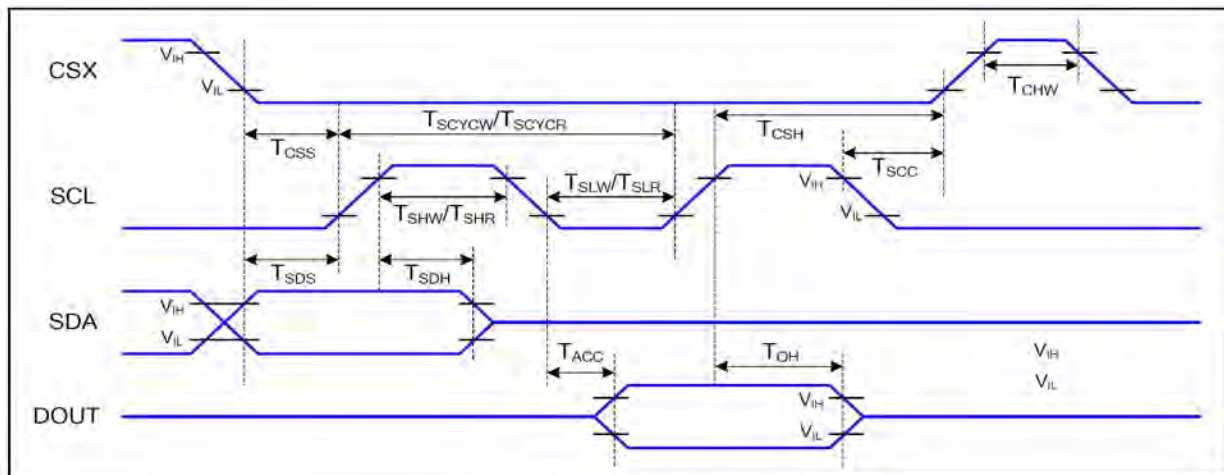


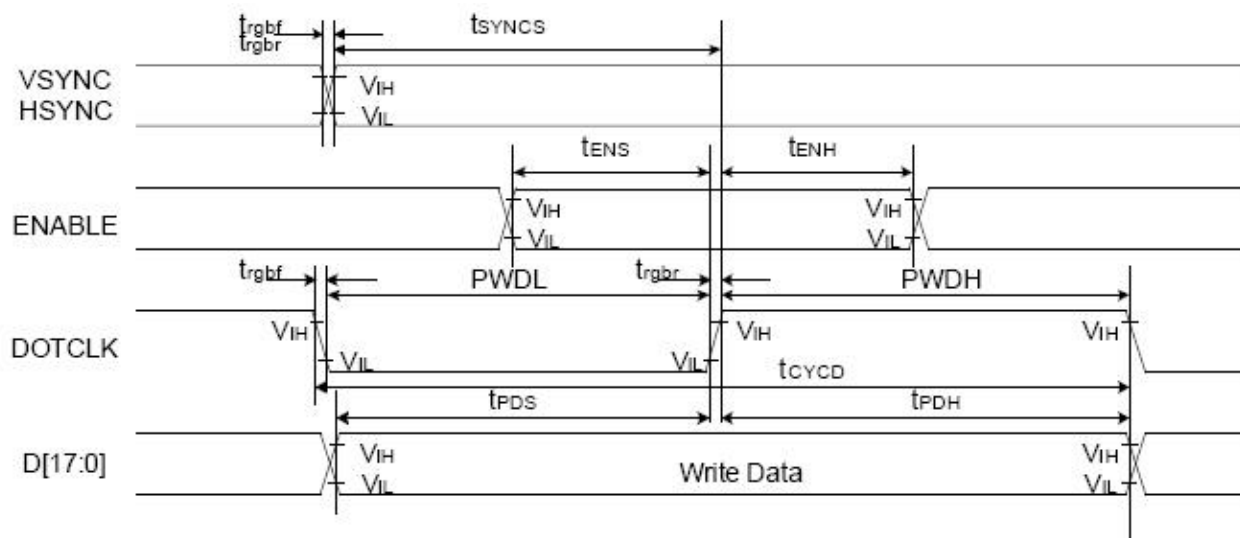
Figure 1 3-line serial Interface Timing Characteristics

VDDI=1.8, VDD=2.8, AGND=DGND=0V, Ta=25°C

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	60		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	

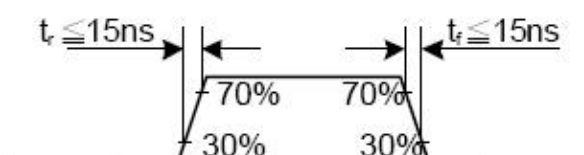
Table 4 3-line serial Interface Characteristics

8.4 RGB interface characteristic



Signal	Symbol	Parameter	min	max	Unit	Description
VSYNC / HSYNC	t_{SYNCs}	VSYNC/HSYNC setup time	15	-	ns	18/16-bit bus RGB interface mode
	t_{SYNH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PDH	DOTCLK high-level period	15	-	ns	
	PWL	DOTCLK low-level period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	100	-	ns	
	$t_{\text{rgbr}}, t_{\text{rgbfr}}$	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	
VSYNC / HSYNC	t_{SYNCs}	VSYNC/HSYNC setup time	15	-	ns	6-bit bus RGB interface mode
	t_{SYNH}	VSYNC/HSYNC hold time	15	-	ns	
DE	t_{ENS}	DE setup time	15	-	ns	
	t_{ENH}	DE hold time	15	-	ns	
D[17:0]	t_{POS}	Data setup time	15	-	ns	
	t_{PDH}	Data hold time	15	-	ns	
DOTCLK	PDH	DOTCLK high-level pulse period	15	-	ns	
	PWL	DOTCLK low-level pulse period	15	-	ns	
	t_{CYCD}	DOTCLK cycle time	50	-	ns	
	$t_{\text{rgbr}}, t_{\text{rgbfr}}$	DOTCLK,HSYNC,VSYNC rise/fall time	-	15	ns	

Note: $T_a = -30$ to 70°C , $V_{\text{DDI}}=1.65\text{V}$ to 3.3V , $V_{\text{CI}}=2.5\text{V}$ to 3.3V , $\text{AGND}=\text{VSS}=0\text{V}$



9. Standard Specification for Reliability

9.1 Standard Specification for Reliability of LCD Module

No.	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C, 90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -20°C for 30 minutes → normal temperature for 5 minutes → +60°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing drop test	According to ASTM-D-5327.
08	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs



9.2 Testing Conditions and Inspection Criteria

For the final test, the testing sample must be stored at room temperature for 24 hours. After the tests listed in Table 9.2, standard specifications for reliability will be executed in order to ensure stability.

No.	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

9.3 MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature ($25\pm5^{\circ}\text{C}$), normal humidity ($50\pm10\%$ RH), and in area not exposed to direct sun light.
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10. Specification of Quality Assurance

This standard of Quality Assurance confirms to the quality of LCD module products supplied by Midas.

10.1 Quality Test

Before delivering, the supplier should conduct the following tests to confirm the quality of products.

- Electrical-Optical Characteristics: According to the individual specification to test the product.
- Appearance Characteristics: According to the individual specification to test the product.
- Reliability Characteristics: According to the definition of reliability on the specification for testing products.

10.2 Delivery Test

Before delivering, the supplier should conduct the delivery test.

- Test method: According to MIL-STD105E.General Inspection Level II take a single time.
- The defects classify of AQL as following:
Major defect: AQL = 0.65
Minor defect: AQL = 2.5
Total defects: AQL = 2.5

10.3 Non-conforming Analysis & Feedback

10.3.1 Non-conforming Analysis

- Purchaser should provide the data detail of non-conforming sample and the non-conforming.
- After receiving the data detail from purchaser, the analysis of non-conforming should be finished within two weeks.
- If the analysis can't be finished on time, supplier must notice purchaser 3 days in advance.

10.3.2 Disposition of non-conforming

- If any product defect be found during assembling, supplier must change the good for every defect after confirmation.
- Both supplier and customer should analyze the reason and discuss the disposition of non-conforming when the reason of nonconforming is not sure.



10.4 Agreement items

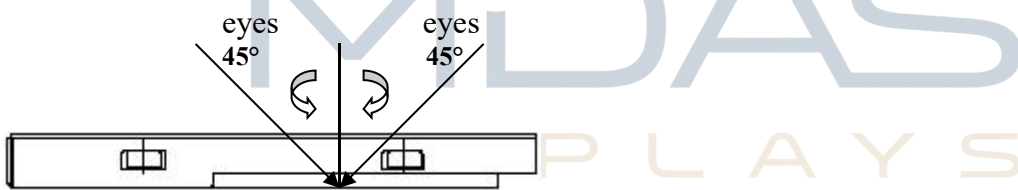
Both parties should negotiate together when the following problems happen.

- There is any problem of standard of quality assurance, and both sides should agree that it must be modified.
- There is any argument item which does not record in the standard of quality assurance.
- Any other special problem.

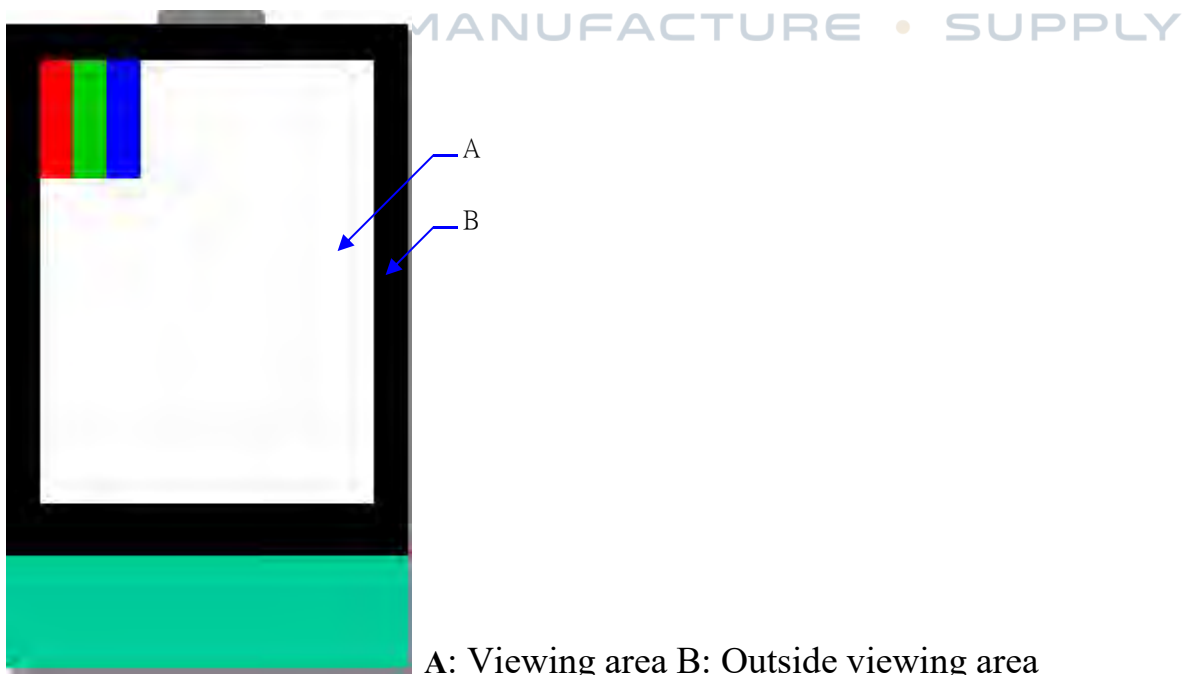
10.5 Standard of the Product Appearance Test

10.5.1 Manner of appearance test

- The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- When test the model of transmissive product must add the reflective plate.
- The test direction is base on around 45° of vertical line.
- Temperature: 25±5°C Humidity: 60±10%RH



- Definition of area: _____



A: Viewing area B: Outside viewing area

10.5.2 Basic principle

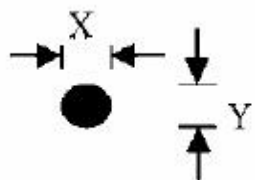
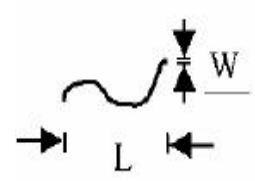
- When the standard cannot be described, AQL will be applied.
- The sample of the lowest acceptable quality level must be negotiated by both supplier and customer when any dispute happened.
- New item must be added on time when it is necessary.

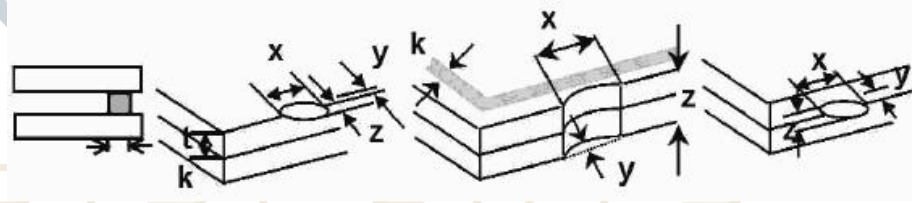
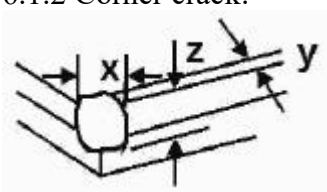


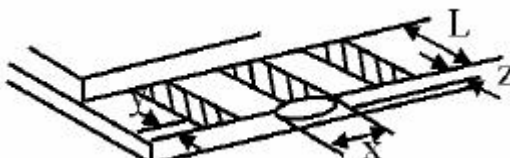
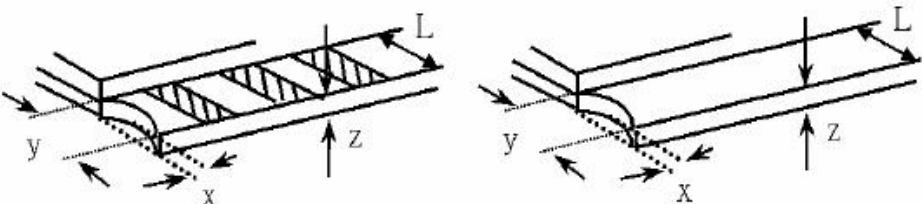
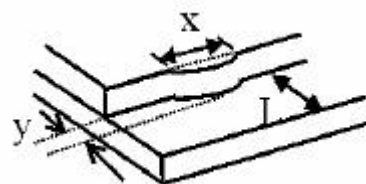
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10.6 Inspection Specification

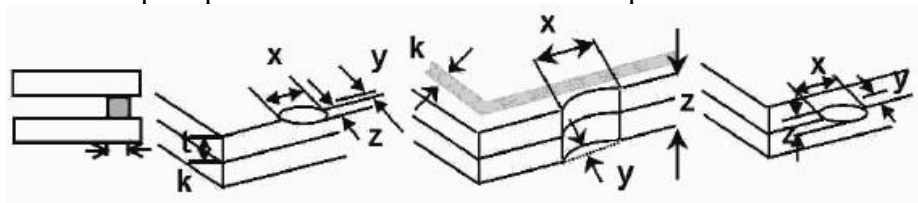
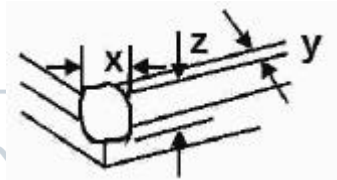
NO.	Item	Criterion	AQL																										
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65																										
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm.	2.5																										
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table><thead><tr><th>Size(mm)</th><th>Acceptable Q'ty</th></tr></thead><tbody><tr><td>$\Phi \leq 0.10$</td><td>Accept no dense</td></tr><tr><td>$0.10 < \Phi \leq 0.20$</td><td>2</td></tr><tr><td>$0.20 < \Phi \leq 0.25$</td><td>2</td></tr><tr><td>$0.25 < \Phi \leq 0.30$</td><td>1</td></tr><tr><td>$0.30 < \Phi$</td><td>0</td></tr></tbody></table> * Densely spaced: No more than two spots within 3mm. 3.2 Line type: (As following drawing)  <table><thead><tr><th>Length(mm)</th><th>Width(mm)</th><th>Acceptable Q'ty</th></tr></thead><tbody><tr><td>---</td><td>$W \leq 0.02$</td><td>Accept no dense</td></tr><tr><td>$L \leq 3.0$</td><td>$0.02 < W \leq 0.05$</td><td rowspan="2">2</td></tr><tr><td>$L \leq 2.5$</td><td>$0.03 < W \leq 0.08$</td></tr><tr><td>---</td><td>$0.08 < W$</td><td>Rejection</td></tr></tbody></table> * Densely spaced: No more than two lines within 3mm.	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	2.5
Size(mm)	Acceptable Q'ty																												
$\Phi \leq 0.10$	Accept no dense																												
$0.10 < \Phi \leq 0.20$	2																												
$0.20 < \Phi \leq 0.25$	2																												
$0.25 < \Phi \leq 0.30$	1																												
$0.30 < \Phi$	0																												
Length(mm)	Width(mm)	Acceptable Q'ty																											
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---	$0.08 < W$	Rejection																											

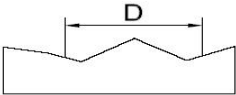
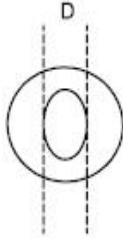
NO.	Item	Criterion			AQL
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction	Size Φ (mm)	Acceptable Q'ty	2.5
			$\Phi \leq 0.20$	Accept no dense	
			$0.20 < \Phi \leq 0.50$	3	
			$0.50 < \Phi \leq 1.00$	2	
			$1.00 < \Phi$	0	
			Total Q'ty	3	
05	Scratches	Follow NO.3 -2 Line Type.			
06	Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:			2.5
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 6.1.2 Corner crack:			
					
		z: Chip thickness	y: Chip width	x: Chip length	
		$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	
		$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	
		⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip			

NO.	Item	Criterion	AQL																
07	Glass crack	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 7.2 Protrusion over terminal: 7.2.1 Chip on electrode pad:  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> 7.2.2 Non-conductive portion:  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> ⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged. 7.2.3 Substrate protuberance and internal crack  <table> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$X \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO.	Item	Criterion	AQL
08	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
09	Backlight elements	9.1 Illumination source flickers when lit. 9.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 9.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
10	Bezel	Bezel must comply with product specifications.	2.5
11	PCB、COB	11.1 COB seal may not have pinholes larger than 0.2mm or contamination. 11.2 COB seal surface may not have pinholes through to the IC. 11.3 The height of the COB should not exceed the height indicated in the assembly diagram. 11.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 11.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 11.6 The jumper on the PCB should conform to the product characteristic chart.	2.5 2.5 2.5 2.5 0.65 0.65
12	FPC	12.1 FPC terminal damage $\leq$ 1/2 FPC terminal width and can not affect the function, we judge accept. 12.2 FPC alignment hole damage $\leq$ 1/2 alignment area and can not affect the function, we judge accept.	2.5 2.5
13	Soldering	13.1 No cold solder joints, missing solder connections, oxidation or icicle. 13.2 No short circuits in components on PCB or FPC.	2.5 0.65



NO.	Item	Criterion	AQL												
14	Touch Panel Chipped glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length 14.1 General glass chip: 14.1.1 Chip on panel surface and crack between panels:  <table> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip 14.1.2 Corner crack:  <table> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> ⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO.	Item	Criterion	AQL										
15	Touch Panel(Fish eye、dent and bubble on film)	<table> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </table>  	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
16	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion ($\leq 2.5\%$) , it is acceptable.	2.5										
17	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
18	LCD Ripple	Touch the touch panel, cannot see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
19	General appearance	19.1 Pin type must match type in specification sheet. 19.2 LCD pin loose or missing pins. 19.3 Product packaging must the same as specified on packaging specification sheet. 19.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

11. Handling Precaution

11.1 Handling of LCM

- Avoid external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance, do not lick or swallow. When the liquid makes contact with your hand, skin, cloth, etc., wash it thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should wear protections whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface, be careful when peeling off this protective film since static electricity may be generated.

11.2 Storage

- Store it in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\%\text{RH}$. Don't expose to sunlight or fluorescent light.
- Store it in a clean environment, free from dust, active gas, and solvent.
- Store it in anti-static electricity container.
- Store it without any physical load.

11.3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: no higher than $280\pm 10^{\circ}\text{C}$ and less than 3 sec during hand soldering.
- Rewiring: no more than 2 times.

